



Material Content Data Sheet



Sales Product Name		BTS282Z E3230		Issued		19. July 2018		
MA#		MA001137292						
Package		PG-TO220-7-12		Weight*		2123.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.825	0.65	0.65	6509	6509
leadframe	non noble metal	iron	7439-89-6	0.908	0.04		428	
	inorganic material	phosphorus	7723-14-0	0.272	0.01		128	
	non noble metal	copper	7440-50-8	906.793	42.70	42.75	426951	427508
wire	non noble metal	aluminium	7429-90-5	4.353	0.20	0.20	2050	2050
encapsulation	organic material	carbon black	1333-86-4	8.740	0.41		4115	
	plastics	epoxy resin	-	96.140	4.53		45266	
	inorganic material	silicondioxide	60676-86-0	477.789	22.50	27.44	224960	274341
leadfinish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10832	10832
plating	non noble metal	nickel	7440-02-0	0.216	0.01		102	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	102
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	74	74
solder	noble metal	silver	7440-22-4	0.202	0.01		95	
	non noble metal	tin	7440-31-5	0.162	0.01		76	
	non noble metal	lead	7439-92-1	7.732	0.36	0.38	3641	3812
heatspreader	non noble metal	iron	7439-89-6	0.584	0.03		275	
	inorganic material	phosphorus	7723-14-0	0.175	0.01		82	
	non noble metal	copper	7440-50-8	582.824	27.44	27.48	274415	274772
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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